



# **iMAPS IBERIA SUMMIT 2026**

## **& MICROELECTRONIC WORKSHOP**

// June 11-12, 2026 //

Vilanova i la Geltrú. Barcelona. Spain

### **AGENDA**

**08:30 - 09:00 | Welcome Reception****09:00 - 09:30 | Institutional Presentations**

**Albert Casas.** iMAPS Iberia President.

**Xavier Roca.** Director-General for Industry, Government of Catalonia.

**Anna Ribera.** Councillor for Urban Planning, Capital Status and Business. Vilanova i la Geltrú Town Council.

**AESEMI.** Spanish Semiconductor Association.

**09:30 - 11:00 | Research Technological Advanced Packaging**

**Power Chip-Embedding: IMB-CNM (CSIC) Activities within the SCAPE Project.** *Emma Solà Marimon.* PhD Student in Electronic Engineering. **CNM.**

**Ongoing R&D Projects. Innovation in Microelectronics Production Solutions.** *David Paris.* R&D Director. **MSTECH Europe.**

**Advanced Packaging for Superconducting Quantum Processors.** *Volkan Tozan.* Electronic Engineer. **Qilimanjaro Quantum Tech.**

**BACK-X. AI-Driven Data Space for Electronics Manufacturing.** *Elio Saltalamacchia.* CIO. **ONIZEA. MSTECH Europe. UC3M.**

**11:00 - 11:30 | Coffee Break****11:30 - 12:50 | Micro-Assembly and Packaging Processes**

**Process Wire Bonding Technology.** *Tobias Hickmann.* Wire Bonding Process Expert. CEO. **TPT.**

**An Innovative Contactless Technology for High Resolution, High Speed, Conductive & Di-electric Materials Deposition.** *Stéphane Etienne.* Senior Advisor, Strategic Accounts. **ioTech.**

**Sub-10  $\mu\text{m}$  Additive Repair of Advanced Interconnects for Yield Improvement.** *Kamelia Kowalczywska.* Senior Business Development Specialist. **XTPL.**

**Dispensing and Plasma Treatment for Semiconductor.** *Maarten Haegdorens.* Senior Expert in Dispensing Technologies. **Nordson Asymtek.**

**11:30 - 12:50 | Micro-Assembly and Packaging Processes**

**Addressing Testing Challenges for the Diversified Semiconductor Industry.** *Fabio Sollazzo.* Semiconductor Test Expert. **Spea.**

**12:50 - 13:30 | Live Process Demo Tour****13:30 - 14:30 | Lunch Break****14:30 - 15:20 | Micro-Assembly and Packaging Processes**

**Optical Inspection for Advanced Packaging.** *Jesús Rubio González.* Product & App. Manager. **MSTECH Europe.**

**Wafer Treatment Process.** *Yossi Gershon.* VP Sales. **ADT.**

**No Cleanroom, No Semiconductors: Protecting the Manufacturing Process.** *Fernando Cajal.* Business Development. Special Projects. **Valtria.**

**15:20 - 16:00 | Live Process Demo Tour****16:00 - 16:20 | Coffee Break****16:20 - 17:00 | Roundtable:**

**Advanced Packaging in Europe: Skills, Strategy and Infrastructure.**

**Advanced Packaging Training.** *Antonio Rubio.* Emeritus Professor. **UPC.**

**Presidency of the European Semiconductor Regions Alliance.** *Roger Costa.* **ACCIO.**

**European Pilot Line APECS.** *Luis Fonseca.* Director. **IMB-CNM.**

**17:00 - 17:30 | Wrap-Up & Closing Discussion****17:30 - 19:30 | Cultural Activity in Vilanova i la Geltrú****20:00 - | Beach Dinner (optional)**

08:30 - 09:00 | Welcome Reception

09:00 - 09:30 | MicroNanoSpain.

The Spanish Semiconductor Competence Centre.  
**Sergio Vicente**. Project Manager. MicroNanoSpain. **AESEMI**.

09:30 - 13:30 | Technical Demos (Group Rotation – 3 Parallel Areas + 1 Exhibitor Area)

09:30 - 10:30

Zone 4 / Clean Room - Group 1

- **Ultra-Precise Dispensing for Advanced Packaging: from Lab to Fab.** *Iwona Grądzka-Kurzaj*. Implementation & Service Engineer. **XTPL**.
- **Laser Additive Deposition. IO300.** *Jordi Pino*. Project Manager R&D. MSTECH Europe. **ioTech**.
- **No Cleanroom, No Semiconductors: Protecting the Manufacturing Process.** *Fernando Cajal*. Business Development. Special Projects. **Valtria**.

Zone 5 / Chiplet Area - Group 2

- **Semiconductor Inspection. SEMINFINITY.** *Jesús Rubio González*. Product & App. Manager. **MSTECH Europe**.
- **Wire Bonding Process. HB16.** *Tobias Hickmann*. Wire Bonding Process Expert. CEO. **TPT**.
- **Dicing System.** *Yossi Gershon*. VP Sales. **ADT**.

Zone 6 / Demo Room - Group 3

- **Fluid Dispenser. Plasma Treatment. Quantum.** *Maarten Haegdorens*. Senior Expert in Dispensing Technologies. **Nordson Asymtek**. **Nordson March**.
- **One-to-One Technical Discussions on SPEA Testing Solutions.** *Fabio Sollazzo*. Semiconductor Test Expert. **SPEA**.

10:30 - 11:30

Zone 4 / Clean Room - Group 2

- XTPL | ioTech | Valtria.

Zone 5 / Chiplet Area - Group 3

- MSTECH Europe | TPT | ADT.

Zone 6 / Demo Room - Group 1

- Nordson Asymtek | Nordson March | SPEA.

11:30 - 12:30

Zone 4 / Clean Room - Group 3

- XTPL | ioTech | Valtria.

Zone 5 / Chiplet Area - Group 1

- MSTECH Europe | TPT | ADT.

Zone 6 / Demo Room - Group 2

- Nordson Asymtek | Nordson March | SPEA.

12:30 - 13:30

Exhibitor Area

- XTPL | ioTech | Valtria | MSTECH Europe | TPT | ADT | Nordson Asymtek | Nordson March | SPEA.

13:30 – 14:30 | Lunch Catering & Networking



## EXHIBITORS

### ADT



**Yossi Gershon**

Advanced dicing technologies for complex semiconductor, microelectronics and optical component manufacturing, addressing precision, reliability and process performance, and high-volume production yield optimization.

### IOTECH



**Stéphane Etienne**

ioTech's CLAD technology enables sustainable, high-resolution laser-assisted selective deposition, reducing acid and water use while offering a digital alternative to solder paste printing for semiconductor packaging.

### MSTECH Europe



**Jesús Rubio**

MSTECH Europe. Backend solutions and high-end integration of production systems for the microelectronics industry.

### Nordson Electronics Solutions



**Maarten Haegdorens**

Advanced fluid dispensing and plasma surface treatment for semiconductor manufacturing, supporting smaller, more powerful and reliable chips.

### SPEA



**Fabio Sollazzo**

Advanced testing strategies for heterogeneous semiconductor architectures, integrating dedicated instrumentation and diagnostics for MEMS, Power, Mixed-Signal and Silicon-Photonics devices.

### TPT



**Tobias Hickmann**

Wire bonding technologies for semiconductor interconnection, addressing ball and wedge bonding, advanced wire materials, process reliability and trends toward miniaturized, high-performance devices.

### XTPL



**Kamelia Kowalczywska**

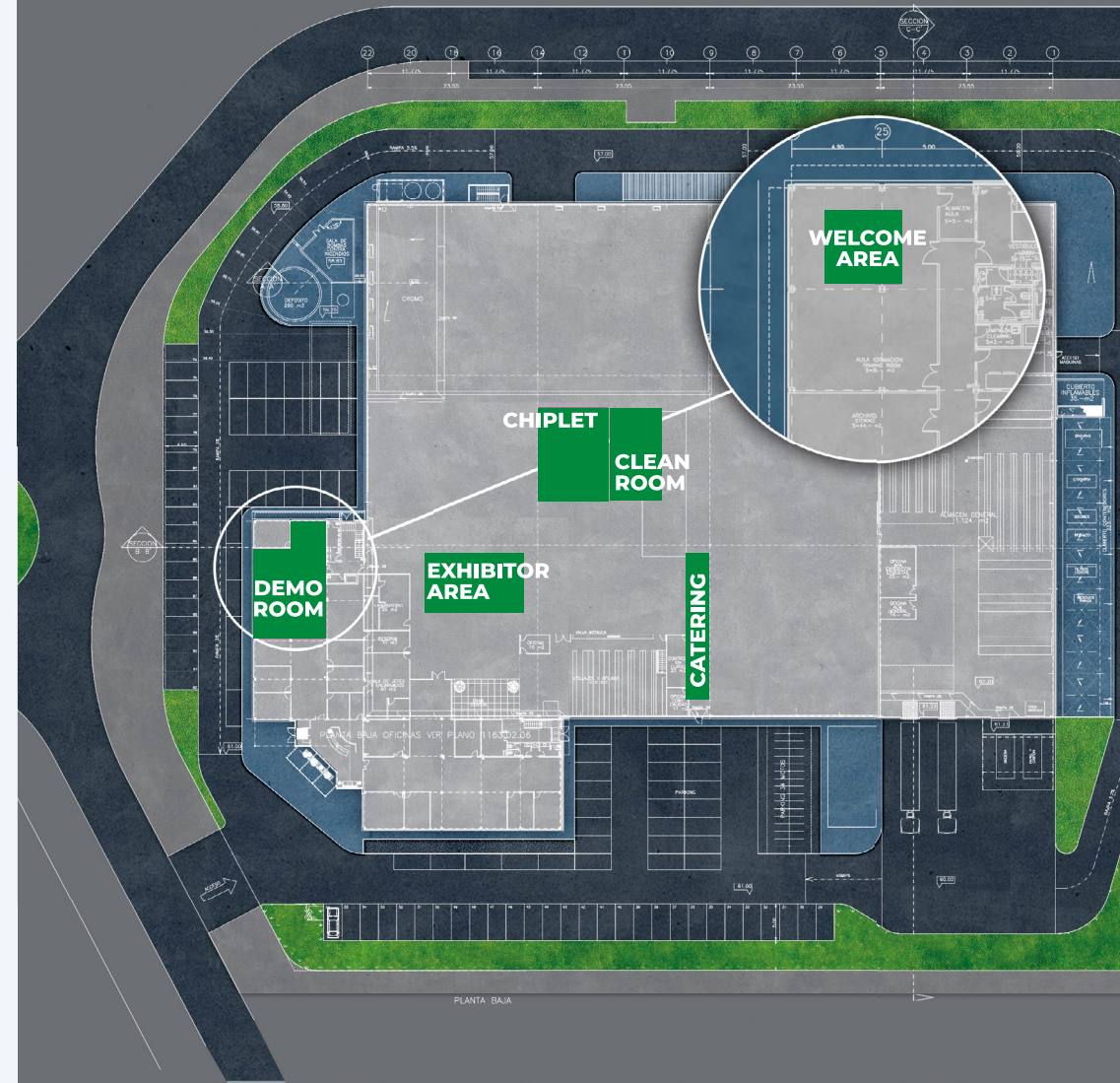
Ultra-Precise Dispensing for advanced packaging, addressing sub-10 µm interconnect repair, RDL restoration, 3D reconstruction, circuit editing and yield improvement.

### VALTRIA



**Fernando Cajal**

Turnkey cleanroom infrastructure for semiconductor manufacturing, protecting wafer processes through contamination control, HVAC, real-time monitoring and energy efficiency.



### WELCOME AREA

### DEMO ROOM

Nordson Asymtek  
Nordson March  
SPEA

### CHIPLET

MSTECH Europe  
TPT  
ADT

### CLEAN ROOM

XTPL  
ioTech  
Valtria

### EXHIBITOR AREA

ADT | ioTech | MSTECH Europe | Nordson Asymtek | Nordson March | XTPL | SPEA | TPT | Valtria



IN COLLABORATION WITH



AJUNTAMENT DE  
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